

SOT1991-3(D)

HTQFN24, thermal enhanced thin quad flat package; no leads; dimple wettable flank; 24 terminals, 0.5 mm pitch, 4 mm x 4 mm x 1 mm body

8 May 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFN24
Package style descriptive code	HTQFN (thermal enhanced thin quad flatpack; no leads)
Mounting method type	S (surface mount)
Issue date	11-04-2019
Manufacturer package code	98ASA01399D

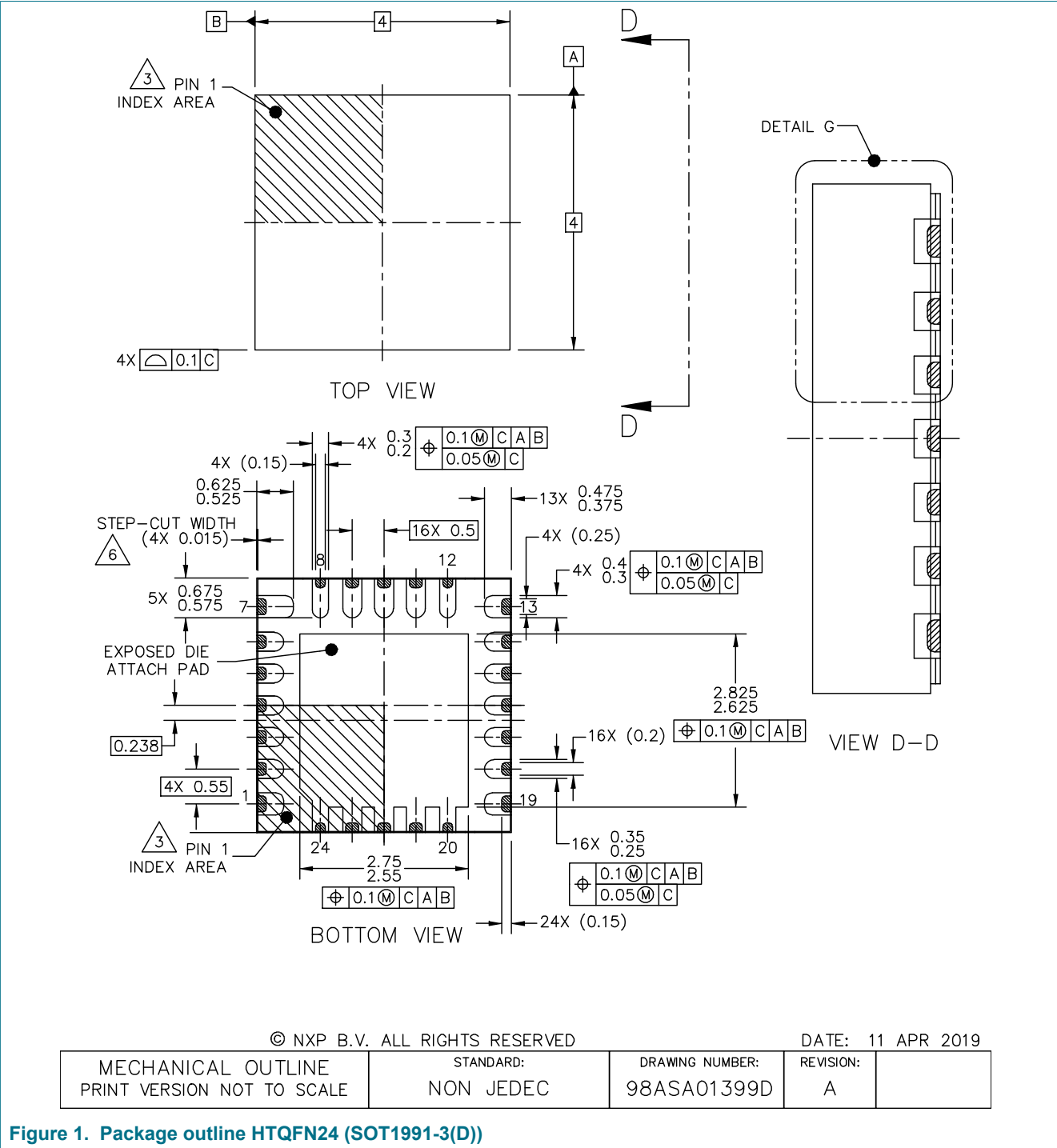
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	4	-	mm
package width	-	4	-	mm
seated height	-	1	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	24	-	

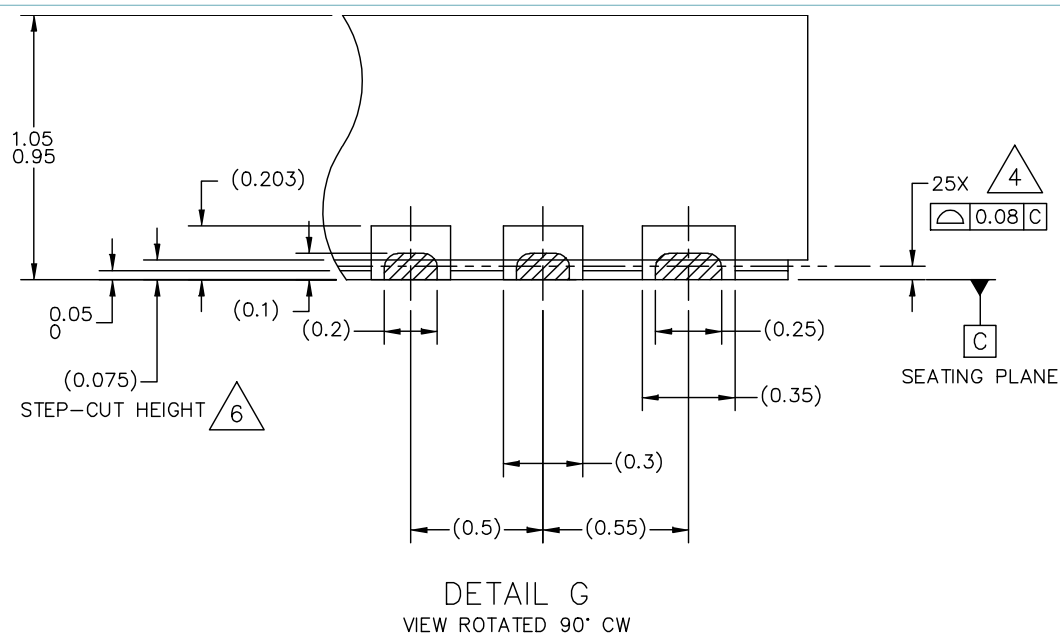


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2 Package outline



HTQFN24, thermal enhanced thin quad flat package; no leads; dimple wettable flank; 24 terminals, 0.5 mm pitch, 4 mm x 4 mm x 1 mm body



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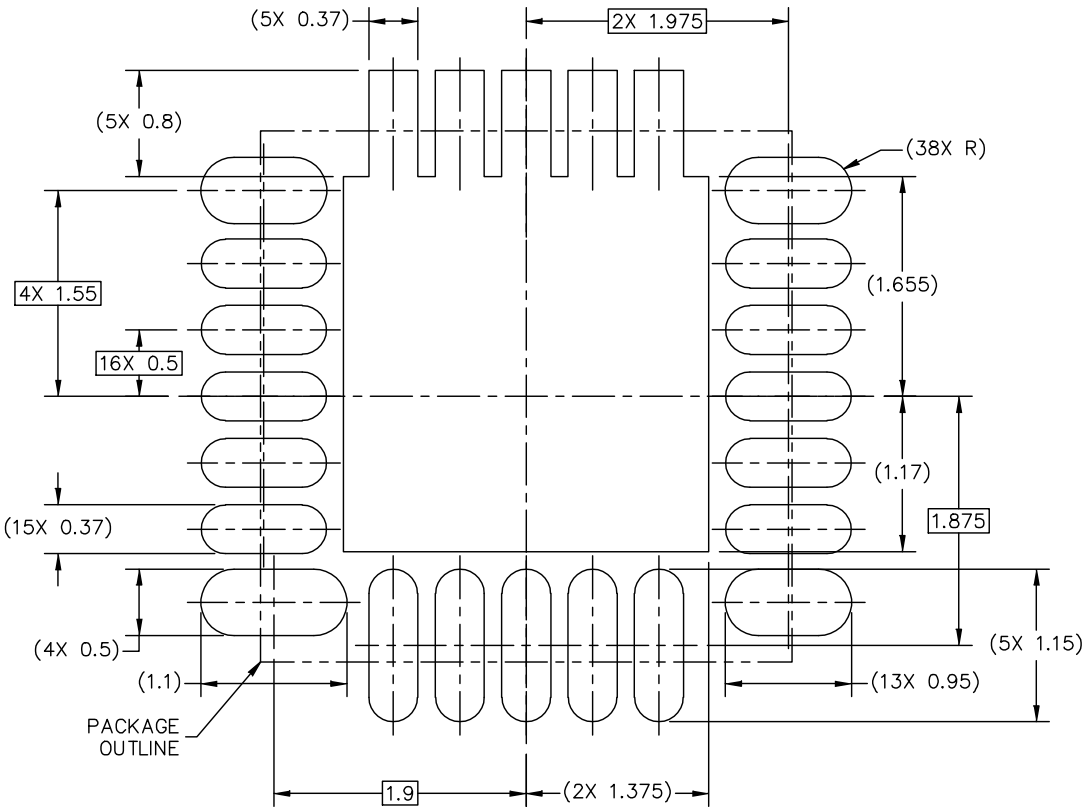
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Figure 2. Package outline detail HTQFN24 (SOT1991-3(D))

HTQFN24, thermal enhanced thin quad flat package; no leads; dimple wettable flank; 24 terminals, 0.5 mm pitch, 4 mm x 4 mm x 1 mm body

3 Soldering



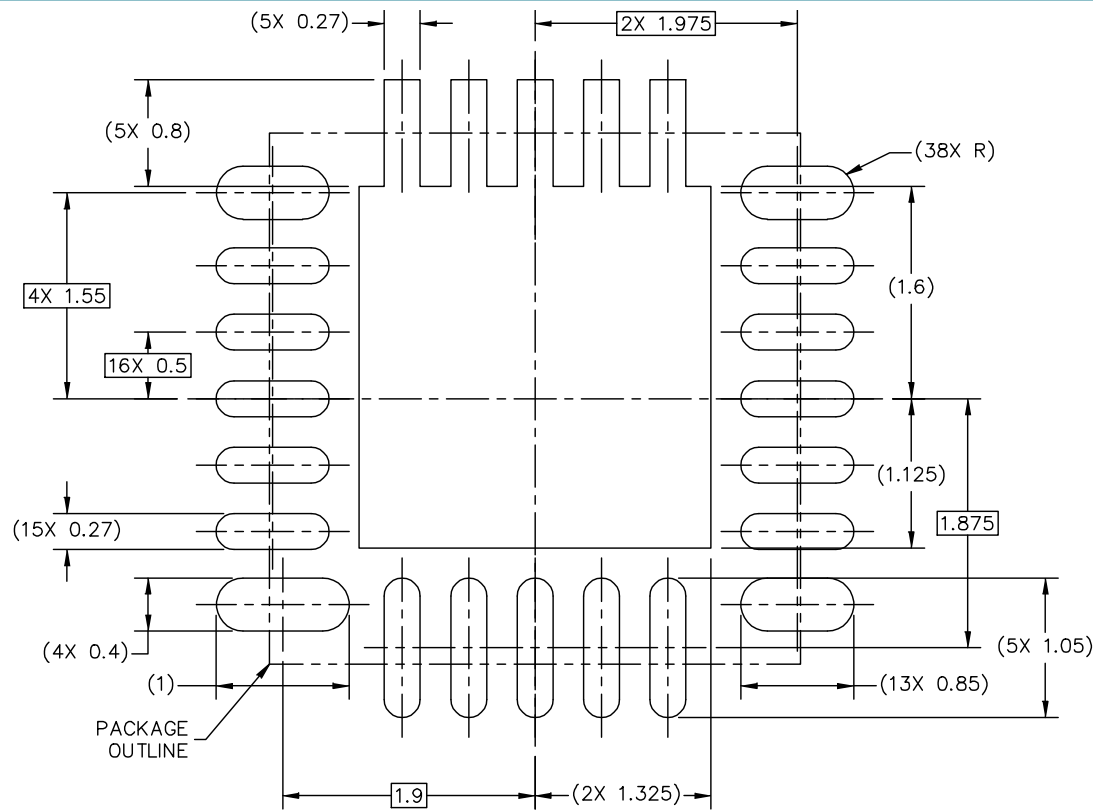
PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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Figure 3. Reflow soldering footprint part1 for HTQFN24 (SOT1991-3(D))

HTQFN24, thermal enhanced thin quad flat package; no leads; dimple wettable flank; 24 terminals, 0.5 mm pitch, 4 mm x 4 mm x 1 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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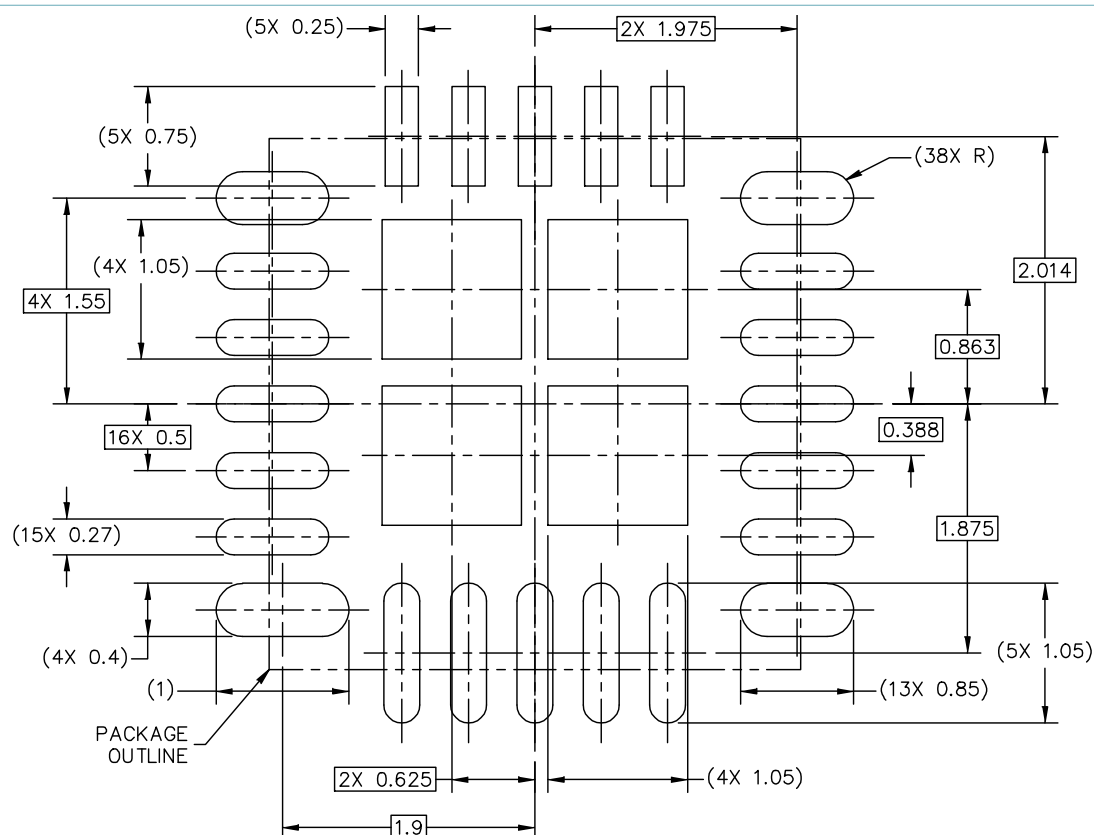
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Figure 4. Reflow soldering footprint part2 for HTQFN24 (SOT1991-3(D))

HTQFN24, thermal enhanced thin quad flat package; no leads; dimple wettable flank; 24 terminals, 0.5 mm pitch, 4 mm x 4 mm x 1 mm body



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HTQFN24 (SOT1991-3(D))

HTQFN24, thermal enhanced thin quad flat package; no leads; dimple wettable flank; 24 terminals, 0.5 mm pitch, 4 mm x 4 mm x 1 mm body

NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
- 5. MIN. METAL GAP SHOULD BE 0.25 MM.
- 6. STEP-CUT IS APPLIED FOR BURR REMOVAL ONLY.

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Figure 6. Package outline note HTQFN24 (SOT1991-3(D))

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4 Legal information

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